

S606

Thermal Compound



Features

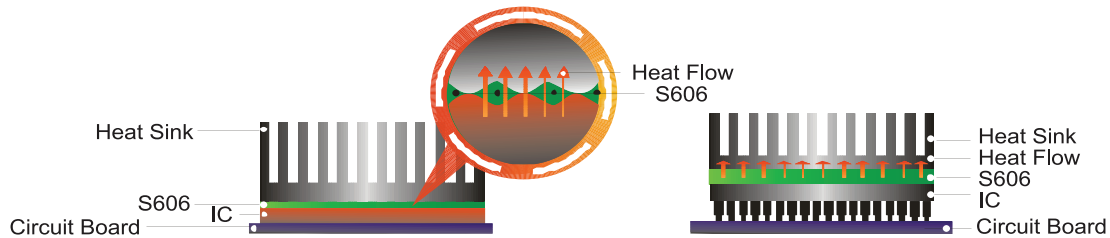
- Good thermal conductivity
- Easy to assemble
- High stability
- Does not harden with time

Applications

- Electronic components: IC / CPU / MOS
- LED / M/B / P/S / Heat Sink / LCD-TV / Notebook PC / PC / Telecom Device / Wireless Hub etc...
- DDR II Module / DVD Applications / Hand-Set applications etc...

Storage

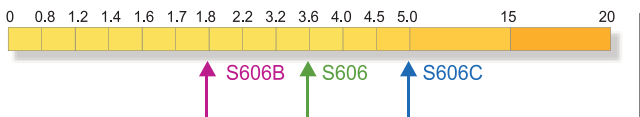
S606 has a self-life of eighteen (18) months from the date of manufacture, as indicated by the lot number, when stored in the original, unopened container at, or below 25 °C.



Properties

- REACH Compliant
- RoHS Compliant

Thermal Conductivity: (W / m.k - Z Axis)



- S606B Thermal Conductivity 1.8 W/m.k
- S606 Thermal Conductivity 3.6 W/m.k
- S606C Thermal Conductivity 5.0 W/m.k

Property	S606	S606B	S606C	Unit	Test Method
Colour	White	White	Grey	-	Visual
Thermal Conductivity	3.6	1.8	5	W/m.k	ASTM D5470
Weight Loss	<0.5	<0.5	<0.5	%	ASTM E595
Specific Gravity	2.3	2.3	2.3	g/cm ³	ASTM D792
Working Temperature	-40~ +180	-40~ +180	-40~ +180	°C	-
Volume Resistance	>10 ¹²	>10 ¹²	>10 ¹²	Ohm-cm	ASTM D257
Standard Package	1kg	1kg	1kg	kg/pot	-

S606(C) - 30 gram
 1. Part Number
 2. Quantity